



# SY88212L

## 3.3V, 2.5Gbps Laser Diode Driver with Integrated Bias and APC

### General Description

The SY88212L is a single supply 3.3V laser driver for datacom and telecom applications with data rates from 155Mbps up to 2.5Gbps. The driver can deliver modulation current up to 85mA, and provides a high compliance voltage that makes it suitable for high-current operation with the laser DC-coupled to it. The drivers have integrated bias and Automatic Power Control (APC) functions.

All support documentation can be found on Micrel's web site at: [www.micrel.com](http://www.micrel.com).

### Features

- 2.4V minimum laser compliance voltage
- Operation up to 2.5Gbps
- Modulation current up to 85mA
- Bias current up to 70mA
- Power monitoring
- Available in 24-pin (4mm x 4mm) QFN package

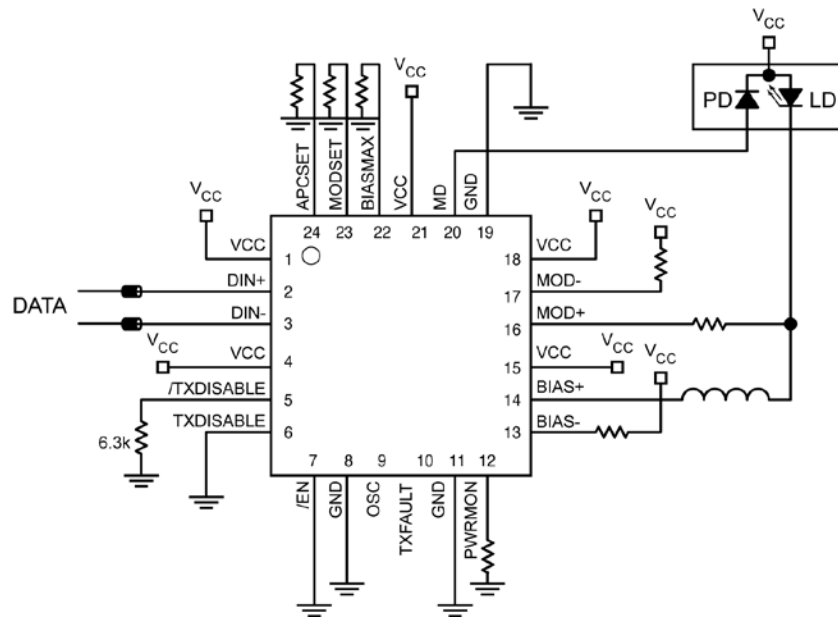
### Applications

- Multi-rate LAN, MAN applications up to 2.5Gbps: FC, GbE, SONET OC3/12/24 and SDH STM1/4/8
- SFF, SFP modules

### Markets

- Telecom, Datacom

### Typical Application



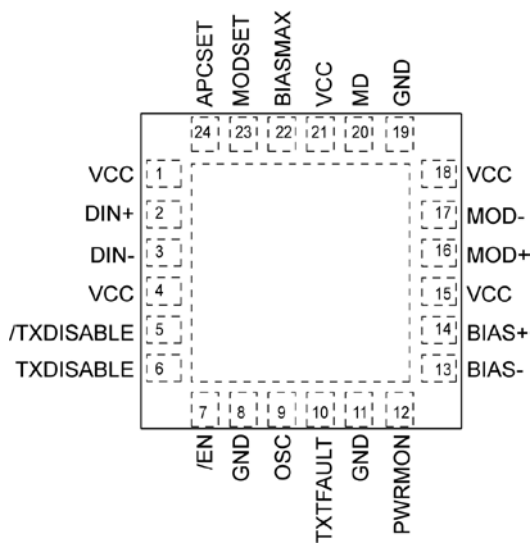
## Ordering Information<sup>(1)</sup>

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY88212LMG	QFN-24	Industrial	212L with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY88212MGTR <sup>(2)</sup>	QFN-24	Industrial	212L with Pb-Free bar-line indicator	NiPdAu Pb-Free

**Notes:**

1. Contact factory for die availability. Dice are guaranteed at T<sub>A</sub> = +25°C, DC Electrical only.
2. Tape and Reel.

## Pin Configuration



**24-Pin QFN**

## Pin Description

Pin Number	Pin Name	Pin Function
2	DIN+	Non-inverting input data. Internally terminated with 50Ω to a reference voltage.
3	DIN-	Inverting input data. Internally terminated with 50Ω to a reference voltage.
5	/TXDISABLE	Transmitter Complementary TXDISABLE. TTL Input. The transmitter is enabled when this pin is asserted High and disabled when this pin is asserted Low. A 6.3kΩ resistor must be installed between pins 6 and GND if /TXDISABLE is used as TTL input
6	TXDISABLE	Transmitter Disable. TTL input. The transmitter is enabled when this pin is asserted Low and disabled when this pin is asserted High or left open. A 6.3kΩ resistor must be installed between pin 5 and GND if TXDISABLE is used as TTL input.
7	/EN	Active low TTL/CMOS. Internally pulled-up. Pull-down with a 22kΩ or lower resistance or apply a low level signal (<0.8 V) to enable bias and modulation. Keep floating or apply a high level (>2 V) to disable.
9	OSC	Internal oscillator setting option. Install a 0Ω resistor from this pin to VCC or leave it open to set the frequency. Refer to the frequency table.
10	TXFAULT	Transmitter Fault Indicator. Open collector. Active High.
12	PWRMON	Power Monitor. Provides a current which is proportional to the sum of bias current and half of modulation current. Install a resistor between this pin and GND to convert that current to a voltage.
13	BIAS-	Inverting laser bias current output. Pull-up to VCC with a resistor.
14	BIAS+	Non-inverting laser bias current output, sources current when TXDISABLE is inserted Low (see pin 6 description) or /TXDISABLE is inserted High (see pin 5 description). Connect to the cathode of the laser through a resistor.
16	MOD+	Non-inverted modulation current output. Provides modulation current when input data is positive.
17	MOD-	Inverted modulation current output. Provides modulation current when input data is negative.
20	MD	Input from the laser monitoring photodiode. Connect to the anode of the photodiode for APC operation.
22	BIASMAX	Install a resistor between this pin and GND to set the maximum bias current for the closed loop operation. The APC loop controls the bias current up to the level of BIASMAX. When the bias current reaches the maximum value set through this pin, the driver continues to sink a current equal to this maximum. For open loop operations, this pin sets the bias current.
23	MODSET	Modulation current setting and control. The modulation current is set by installing an external resistor from this pin to ground or using a current source.
24	APCSET	Bias current setting and control. The bias current is set by installing an external resistor from this pin to ground or using a current source. Connect a 50K resistor to GND for open loop operation.
8, 11, 19	GND	Ground. Ground and exposed pad must be connected to the plane of the most negative potential.
1, 4, 15, 18, 21	VCC	Supply Voltage. Bypass with a 0.1μF//0.01μF low ESR capacitor as close to VCC pin as possible.

## Truth Table

DIN+	DIN-	/EN	MOD+ <sup>(1)</sup>	MOD-	Laser Output <sup>(2)</sup>
L	H	L	H	L	L
H	L	L	L	H	H
X	X	H	H	L	L

### Notes:

- $I_{MOD} = 0$  when MOD+ = H.
- Assuming that the cathode of the laser is tied to MOD+.

## Oscillator Frequency

OSC	Frequency (MHz)
Open	25
VCC	50

**Absolute Maximum Ratings<sup>(1)</sup>**

Supply Voltage ( $V_{CC}$ )	-0.5V to +4.0V
CML Input Voltage ( $V_{IN}$ )	$V_{CC}-1.2V$ to $V_{CC}+0.5V$
TTL Control Input Voltage ( $V_I$ )	0V to $V_{CC}+0.3V$
Lead Temperature (soldering, 20sec.)	+260°C
Storage Temperature ( $T_s$ )	-65°C to +150°C

**Operating Ratings<sup>(2)</sup>**

Supply Voltage ( $V_{CC}$ )	+3.0V to +3.6V
Ambient Temperature ( $T_A$ )	-40°C to +85°C
Package Thermal Resistance <sup>(3)</sup>	
QFN	
( $\theta_{JA}$ ) Still-air	50°C/W
( $\psi_{JB}$ )	30°C/W

**DC Electrical Characteristics**

$T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$  and  $V_{CC} = +3.0\text{V}$  to  $+3.6\text{V}$ . Unless otherwise noted, typical values are  $V_{CC} = +3.3\text{V}$ ,

$T_A = 25^\circ\text{C}$ ,  $I_{MOD} = 25\text{mA}$ ,  $I_{BIAS} = 20\text{mA}$ .

Symbol	Parameter	Condition	Min	Typ	Max	Units
$I_{CC}$	Power Supply Current	Modulation and Bias currents excluded		55	95 <sup>(4)</sup>	mA
$V_{MOD\_MIN}$	Minimum Voltage Required at the Driver Output, MOD+ and MOD-, for Proper Operation		0.6			V
$V_{BIAS\_MIN}$	Minimum Voltage Required at the Driver Output, BIAS+ and BIAS-, for Proper Operation		0.8			V
$I_{BIAS}$	Bias-ON Current	Voltage at Bias pin $\geq 0.8\text{V}$	1		70	mA
$I_{BIAS\_OFF}$	Bias-OFF Current	Current at BIAS pin when /EN is high or TXDISABLE is High			150	$\mu\text{A}$
$R_{IN}$	Input Resistance at DIN+ and DIN-	Single ended	42.5	50	57.5	$\Omega$
$V_{DIFF-IN}$ (DIN)	Differential Input Voltage Swing		100		2400	mV <sub>PP</sub>
$V_{OL}$	APCFAULT Output Low	$I_{OL} = 2\text{mA}$			0.5	V
$I_{OH}$	APCFAULT Output Leakage	$V_{OH} = V_{CC}$			100	$\mu\text{A}$
$V_{IH}$	High Voltage /EN, TXDISABLE, /TXDISABLE		2			V
$V_{IL}$	Low Voltage /EN, TXDISABLE, /TXDISABLE				0.8	V
$V_{PWRMON}$	Maximum voltage at PWRMON pin		1.25			V
$I_{MD}$	Current range at MD pin		50		1500	$\mu\text{A}$

**Notes:**

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package Thermal Resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB.  $\psi_{JB}$  uses a 4-layer and  $\theta_{JA}$  in still air unless otherwise stated.
4.  $I_{CC} = 95\text{mA}$  for worst-case conditions with  $I_{MOD} = 85\text{mA}$ ,  $I_{BIAS} = 70\text{mA}$ ,  $T_A = +85^\circ\text{C}$ ,  $V_{CC} = 3.6\text{V}$ .

## AC Electrical Characteristics

$T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$  and  $V_{CC} = +3.0\text{V}$  to  $+3.6\text{V}$ . Unless otherwise noted, typical values are  $V_{CC} = +3.3\text{V}$ ,

$T_A = 25^\circ\text{C}$ ,  $I_{MOD} = 25\text{mA}$ ,  $I_{BIAS} = 20\text{mA}$ .

Symbol	Parameter	Condition	Min	Typ	Max	Units
	Data Rate	NRZ	0.155		2.5	Gbps
$I_{MOD}$	Modulation Current <sup>(5)</sup>	AC-coupled	10		85	mA
		DC-coupled, voltage at MOD pin $\geq 0.6\text{V}$	10		70 <sup>(6)</sup>	mA
$I_{MOD\_OFF}$	Modulation OFF Current	Current at MOD+ when /EN is high or TXDISABLE is Low			150	$\mu\text{A}$
		Current at MOD- when /EN is high or TXDISABLE is High			150	$\mu\text{A}$
$t_r$	Output Current Rise Time	20% to 80%, $I_{MOD} = 60\text{mA}$		60	85	ps
$t_f$	Output Current Fall Time	20% to 80%, $I_{MOD} = 60\text{mA}$		60	85	ps
Jitter	Total Jitter <sup>(7)</sup>	155Mbps data rate			30	ps <sub>PP</sub>
		622Mbps data rate			30	
		1.25Gbps data rate			30	
		2.5Gbps data rate			30	
$t_{INIT}$	APC Loop Initialization Time	Power up with /EN Low			12	$\mu\text{s}$
		/EN changes from high to low with power ON.			10	$\mu\text{s}$

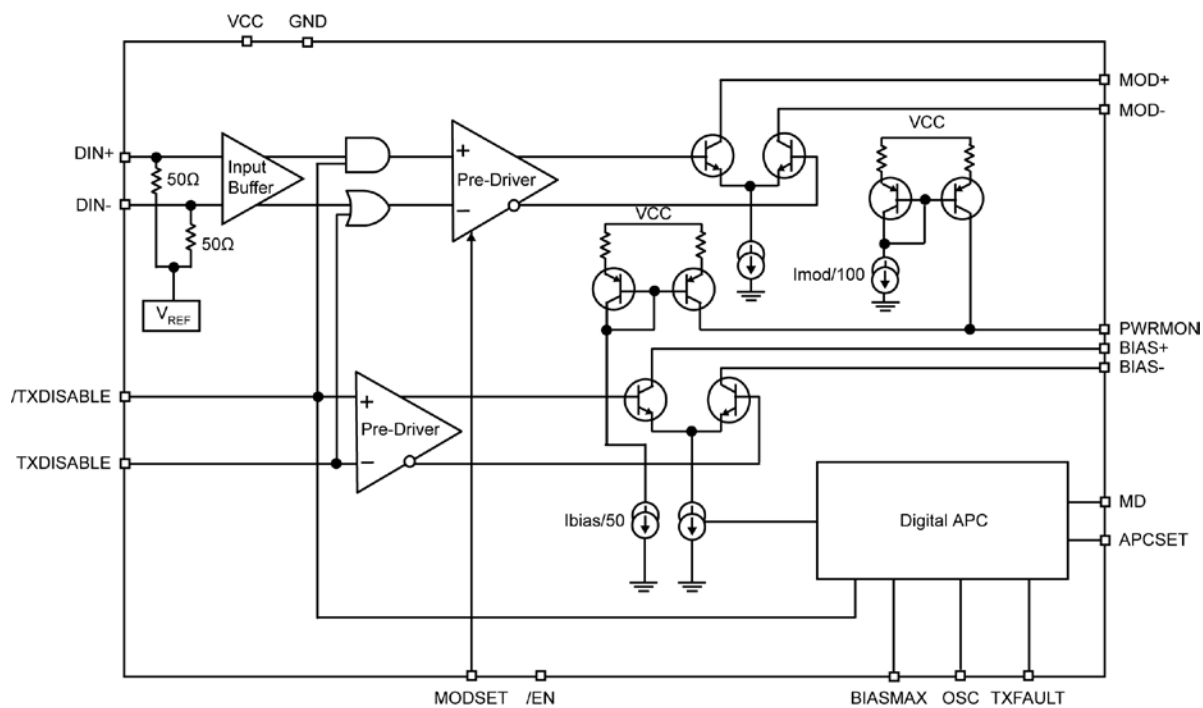
### Notes:

5. Load =  $15\Omega$ .

6. Assuming  $V_{CC} = 3.0\text{V}$ , Laser bandgap voltage =  $1\text{V}$ , laser package inductance =  $1\text{nH}$ , laser equivalent series resistor =  $5\Omega$ , and damping resistor =  $10\Omega$ .

7. Total jitter is measured using  $2^7 - 1$  PRBS pattern.

## Functional Diagram



## Detailed Functional Description

The SY88212L laser driver is comprised from a fast modulator, a fast bias circuit, and a digital APC loop that allows for fast laser turn-ON time. The driver features a power monitoring function.

### BIAS and Modulation Setting

Bias and modulation currents are set by installing resistors from APCSET (pin 24) to ground and from MODSET (pin 23) to ground respectively or by applying a negative current at those pins.  $I_{MD}$  variation versus  $R_{APCSET}$  resistor,  $I_{BIAS}$  variation versus  $R_{BIASMAX}$  resistor, and  $I_{MOD}$  variation versus  $R_{MODSET}$  resistor are shown on page 8.

### BIASMAX

A resistor between BIASMAX pin and ground sets the maximum bias the driver can sink. At normal operation, the bias current tracks the laser optical power through the laser monitoring photodiode and the APC loop to compensate for any power deviation from the nominal value set at the start of operation using APCSET. If for any failure (laser or photodiode degradation, open feedback circuit etc...) the APC loop keeps increasing the bias current trying to compensate for the low power indication, the bias current will stop increasing when it reaches BIASMAX value and continues to operate at that maximum value and TXFAULT asserted high.

BIASMAX also controls the bias current when the circuit is operating in the open loop mode.

### APC Loop Function

At start up, with the driver enabled, the laser turns ON within a few microseconds and its back facet monitoring photodiode starts to generate a photocurrent proportional to the optical power. The photocurrent is fed back to the MD pin on the driver where it's converted to a voltage. The conversion voltage is compared to APCSET on the driver. At equilibrium, the feedback voltage equals the APCSET voltage and the laser optical power reaches its nominal value. If the laser power deviates from its nominal value, the APC loop brings it back to its nominal setting.

### APC Loop Failure

TXFAULT is asserted High if the bias current reaches BIASMAX or if the APC loop counter reaches its minimum or its maximum counts.

### Interfacing the Driver with the Laser Diode

As shown in the "Typical Application" drawing, MOD+ pin is connected to the laser cathode through a 10Ω resistor and MOD- pin is connected to V<sub>CC</sub> with a 15Ω resistor equivalent to 10Ω (damping resistor) in series with the laser (equivalent resistor of 5Ω). The laser can be driven differentially by connecting MOD- to the anode of the laser through 15Ω (15Ω pull-up removed) and isolating the anode of the laser from V<sub>CC</sub> with an inductor.

For better results at 2.5Gbps, the driver can be AC-coupled to the laser as shown in Figure 1.

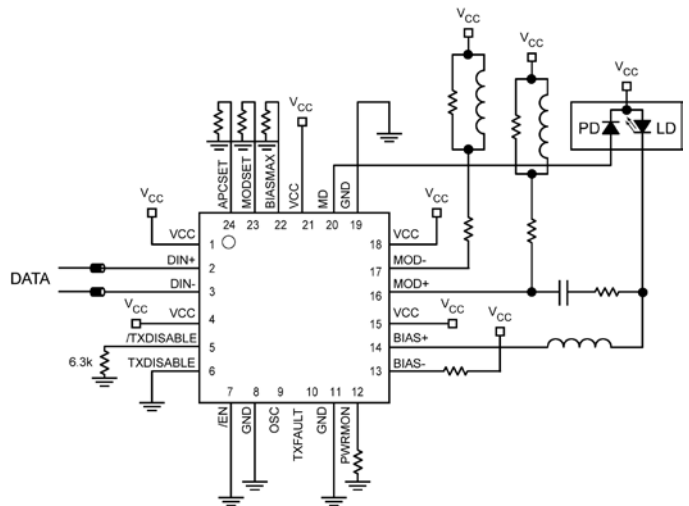
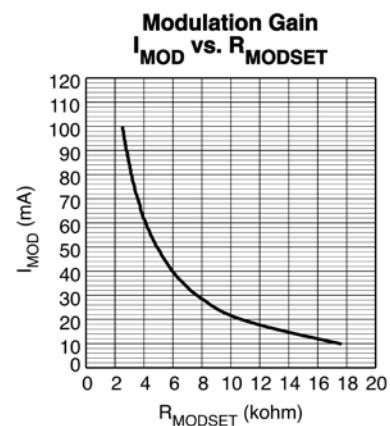
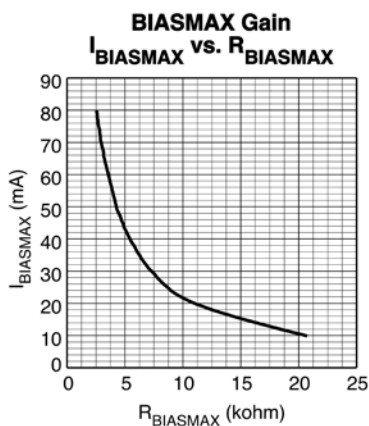
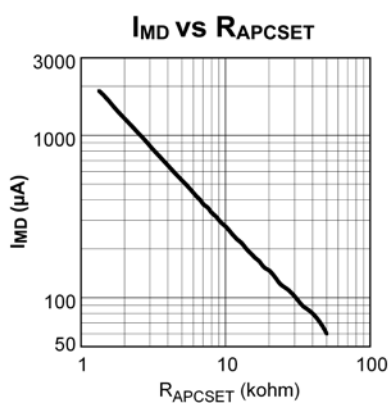
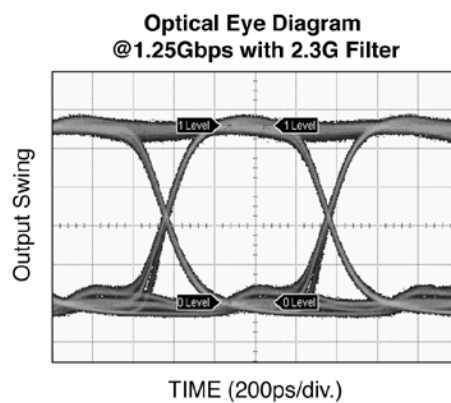
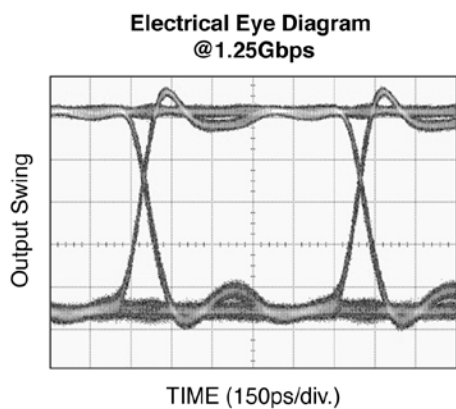


Figure 1. Laser AC-Coupled to the Driver Typical Application

## Typical Characteristics



## Functional Characteristics





## Input and Output Stages

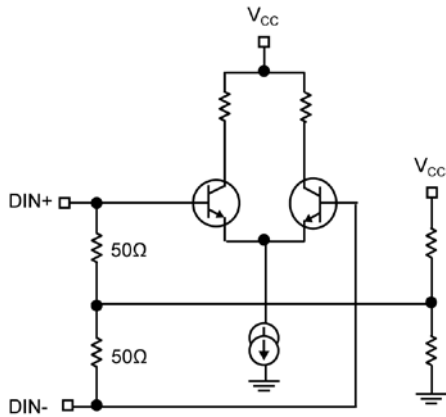


Figure 2a. Simplified Input Stage

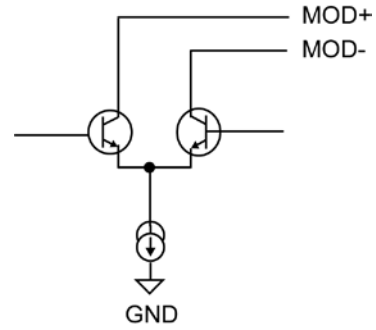


Figure 2b. Simplified Output Stage

## Interfacing DIN Input to Different Logic Drivers

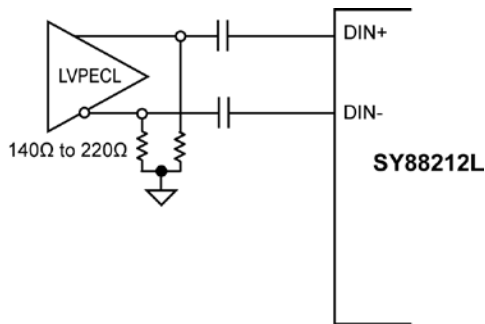


Figure 3a. Driving DIN with PECL Outputs

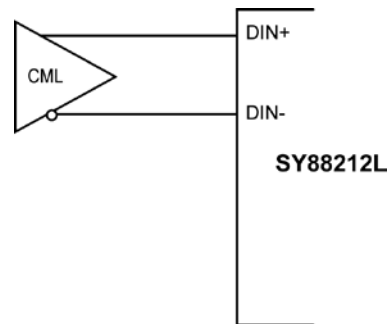
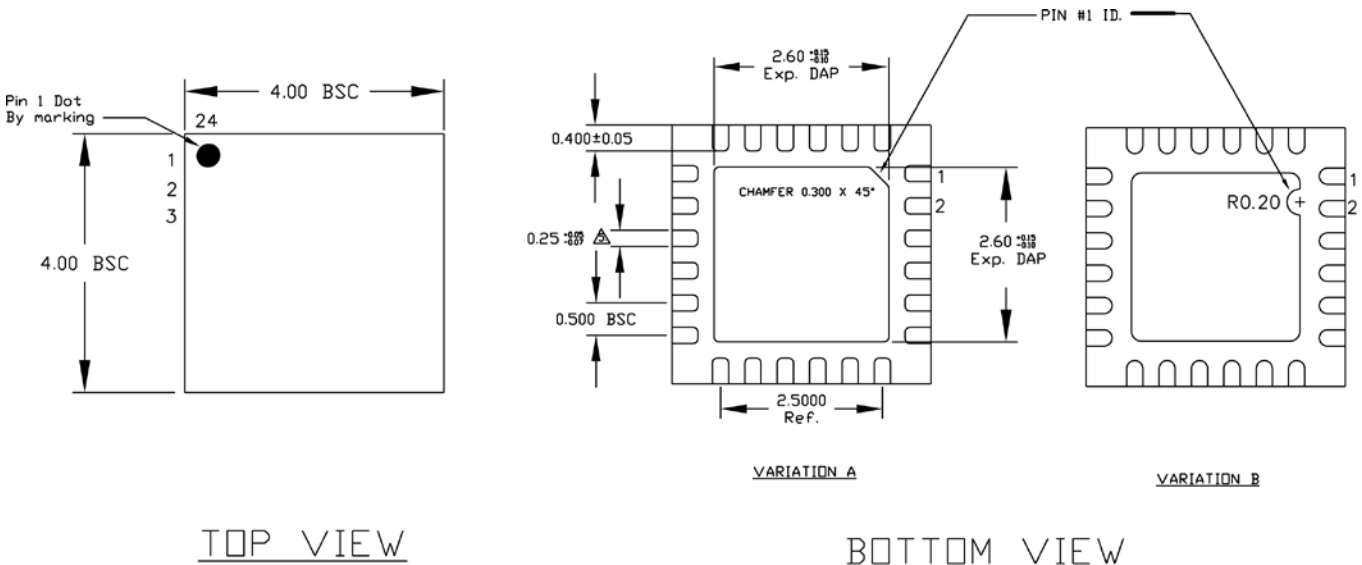


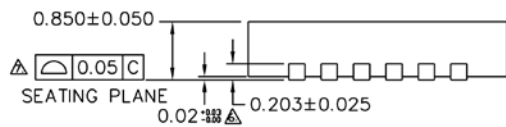
Figure 3b. Driving DIN with CML Outputs

**Package Information**



TOP VIEW

BOTTOM VIEW



SIDE VIEW

**NOTE:**

1. ALL DIMENSIONS ARE IN MILLIMETERS.
  2. MAX. PACKAGE WARPAGE IS 0.05 mm.
  3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
  4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
- △ DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
- △ APPLIED ONLY FOR TERMINALS.
- △ APPLIED FOR EXPOSED PAD AND TERMINALS.

**24-Pin (3mm x 3mm) QFN**

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